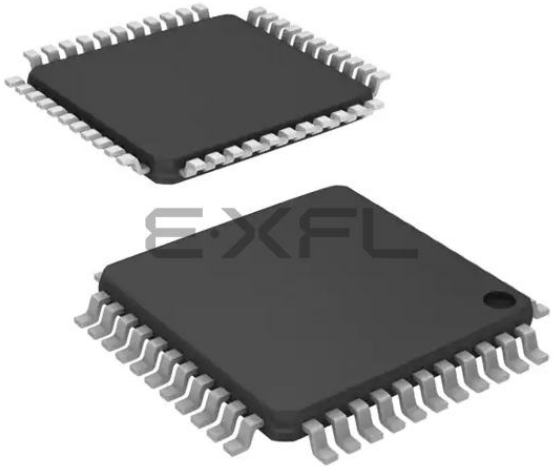

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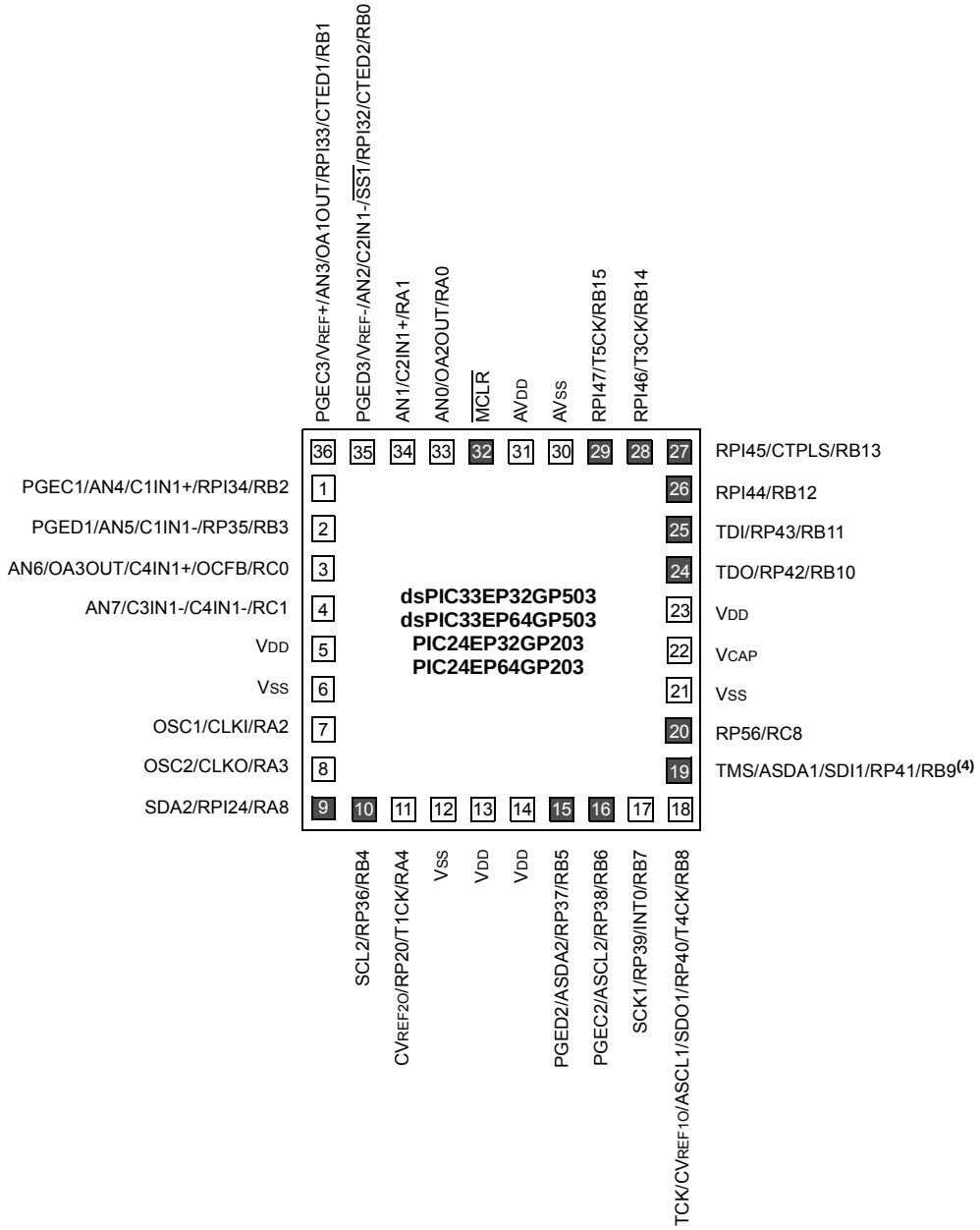
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep256mc204-e-pt

Pin Diagrams (Continued)

36-Pin VTLA(1,2,3)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

FIGURE 4-21: BIT-REVERSED ADDRESSING EXAMPLE

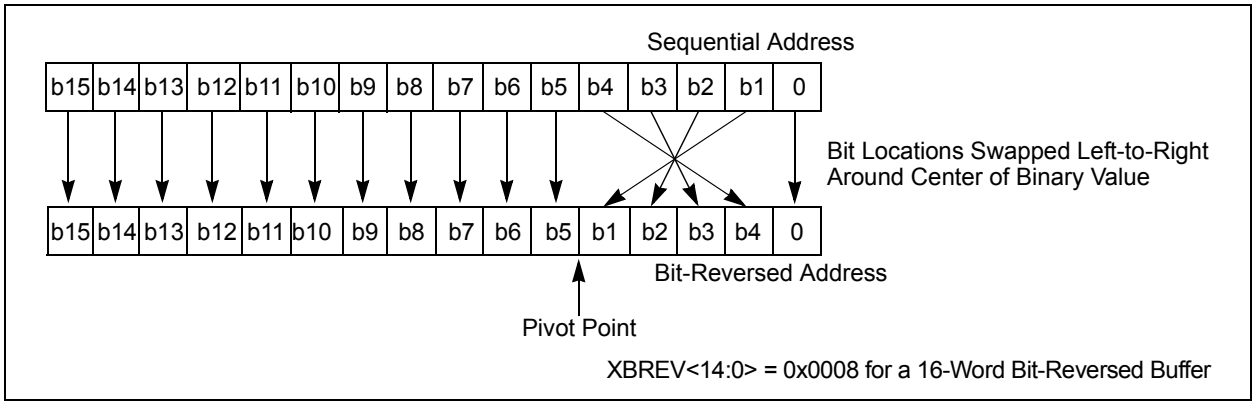


TABLE 4-64: BIT-REVERSED ADDRESSING SEQUENCE (16-ENTRY)

Normal Address					Bit-Reversed Address				
A3	**A2**	**A1**	**A0**	**Decimal**	**A3**	**A2**	**A1**	**A0**	**Decimal**
0	0	0	0	0	0	0	0	0	0
0	0	0	1	1	1	0	0	0	8
0	0	1	0	2	0	1	0	0	4
0	0	1	1	3	1	1	0	0	12
0	1	0	0	4	0	0	1	0	2
0	1	0	1	5	1	0	1	0	10
0	1	1	0	6	0	1	1	0	6
0	1	1	1	7	1	1	1	0	14
1	0	0	0	8	0	0	0	1	1
1	0	0	1	9	1	0	0	1	9
1	0	1	0	10	0	1	0	1	5
1	0	1	1	11	1	1	0	1	13
1	1	0	0	12	0	0	1	1	3
1	1	0	1	13	1	0	1	1	11
1	1	1	0	14	0	1	1	1	7
1	1	1	1	15	1	1	1	1	15

REGISTER 11-5: RPINR8: PERIPHERAL PIN SELECT INPUT REGISTER 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	IC4R<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	IC3R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-8 **IC4R<6:0>:** Assign Input Capture 4 (IC4) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7 **Unimplemented:** Read as ‘0’

bit 6-0 **IC3R<6:0>:** Assign Input Capture 3 (IC3) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

REGISTER 17-10: INDX1HLD: INDEX COUNTER 1 HOLD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INDXHLD<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INDXHLD<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **INDXHLD<15:0>:** Hold Register for Reading and Writing INDX1CNTH bits

REGISTER 17-11: QEI1ICH: QEI1 INITIALIZATION/CAPTURE HIGH WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEIIC<31:24>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEIIC<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **QEIIC<31:16>:** High Word Used to Form 32-Bit Initialization/Capture Register (QEI1IC) bits

REGISTER 17-12: QEI1ICL: QEI1 INITIALIZATION/CAPTURE LOW WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEIIC<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEIIC<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **QEIIC<15:0>:** Low Word Used to Form 32-Bit Initialization/Capture Register (QEI1IC) bits

REGISTER 17-15: QEI1GECH: QEI1 GREATER THAN OR EQUAL COMPARE HIGH WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEIGEC<31:24>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEIGEC<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **QEIGEC<31:16>:** High Word Used to Form 32-Bit Greater Than or Equal Compare Register (QEI1GEC) bits

REGISTER 17-16: QEI1GECL: QEI1 GREATER THAN OR EQUAL COMPARE LOW WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEIGEC<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEIGEC<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **QEIGEC<15:0>:** Low Word Used to Form 32-Bit Greater Than or Equal Compare Register (QEI1GEC) bits

18.3 SPIx Control Registers

REGISTER 18-1: SPIxSTAT: SPIx STATUS AND CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
SPIEN	—	SPISIDL	—	—	SPIBEC<2:0>		
bit 15							bit 8

R/W-0	R/C-0, HS	R/W-0	R/W-0	R/W-0	R/W-0	R-0, HS, HC	R-0, HS, HC
SRMPT	SPIROV	SRXMPT	SISEL2	SISEL1	SISEL0	SPITBF	SPIRBF
bit 7							bit 0

Legend:	C = Clearable bit	HS = Hardware Settable bit	HC = Hardware Clearable bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **SPIEN:** SPIx Enable bit
1 = Enables the module and configures SCKx, SDOx, SDIx and $\overline{SSx}$ as serial port pins
0 = Disables the module

bit 14 **Unimplemented:** Read as '0'

bit 13 **SPISIDL:** SPIx Stop in Idle Mode bit
1 = Discontinues the module operation when device enters Idle mode
0 = Continues the module operation in Idle mode

bit 12-11 **Unimplemented:** Read as '0'

bit 10-8 **SPIBEC<2:0>:** SPIx Buffer Element Count bits (valid in Enhanced Buffer mode)
Master mode:
Number of SPIx transfers that are pending.
Slave mode:
Number of SPIx transfers that are unread.

bit 7 **SRMPT:** SPIx Shift Register (SPIxSR) Empty bit (valid in Enhanced Buffer mode)
1 = SPIx Shift register is empty and Ready-To-Send or receive the data
0 = SPIx Shift register is not empty

bit 6 **SPIROV:** SPIx Receive Overflow Flag bit
1 = A new byte/word is completely received and discarded; the user application has not read the previous data in the SPIxBUF register
0 = No overflow has occurred

bit 5 **SRXMPT:** SPIx Receive FIFO Empty bit (valid in Enhanced Buffer mode)
1 = RX FIFO is empty
0 = RX FIFO is not empty

bit 4-2 **SISEL<2:0>:** SPIx Buffer Interrupt Mode bits (valid in Enhanced Buffer mode)
111 = Interrupt when the SPIx transmit buffer is full (SPITBF bit is set)
110 = Interrupt when last bit is shifted into SPIxSR and as a result, the TX FIFO is empty
101 = Interrupt when the last bit is shifted out of SPIxSR and the transmit is complete
100 = Interrupt when one data is shifted into the SPIxSR and as a result, the TX FIFO has one open memory location
011 = Interrupt when the SPIx receive buffer is full (SPIRBF bit is set)
010 = Interrupt when the SPIx receive buffer is 3/4 or more full
001 = Interrupt when data is available in the receive buffer (SRMPT bit is set)
000 = Interrupt when the last data in the receive buffer is read and as a result, the buffer is empty (SRXMPT bit is set)

REGISTER 21-3: CxVEC: ECANx INTERRUPT CODE REGISTER

U-0	U-0	U-0	R-0	R-0	R-0	R-0	R-0
—	—	—	FILHIT4	FILHIT3	FILHIT2	FILHIT1	FILHIT0
bit 15							bit 8

U-0	R-1	R-0	R-0	R-0	R-0	R-0	R-0
—	ICODE6	ICODE5	ICODE4	ICODE3	ICODE2	ICODE1	ICODE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **FILHIT<4:0>:** Filter Hit Number bits

10000-11111 = Reserved
01111 = Filter 15
•
•
•
00001 = Filter 1
00000 = Filter 0

bit 7 **Unimplemented:** Read as '0'

bit 6-0 **ICODE<6:0>:** Interrupt Flag Code bits

1000101-1111111 = Reserved
1000100 = FIFO almost full interrupt
1000011 = Receiver overflow interrupt
1000010 = Wake-up interrupt
1000001 = Error interrupt
1000000 = No interrupt
•
•
•
0010000-0111111 = Reserved
0001111 = RB15 buffer interrupt
•
•
•
0001001 = RB9 buffer interrupt
0001000 = RB8 buffer interrupt
0000111 = TRB7 buffer interrupt
0000110 = TRB6 buffer interrupt
0000101 = TRB5 buffer interrupt
0000100 = TRB4 buffer interrupt
0000011 = TRB3 buffer interrupt
0000010 = TRB2 buffer interrupt
0000001 = TRB1 buffer interrupt
0000000 = TRB0 buffer interrupt

REGISTER 21-5: CxFIFO: ECANx FIFO STATUS REGISTER

U-0	U-0	R-0	R-0	R-0	R-0	R-0	R-0
—	—	FBP5	FBP4	FBP3	FBP2	FBP1	FBP0
bit 15							bit 8

U-0	U-0	R-0	R-0	R-0	R-0	R-0	R-0
—	—	FNRB5	FNRB4	FNRB3	FNRB2	FNRB1	FNRB0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **FBP<5:0>:** FIFO Buffer Pointer bits

011111 = RB31 buffer
011110 = RB30 buffer
•
•
•
000001 = TRB1 buffer
000000 = TRB0 buffer

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **FNRB<5:0>:** FIFO Next Read Buffer Pointer bits

011111 = RB31 buffer
011110 = RB30 buffer
•
•
•
000001 = TRB1 buffer
000000 = TRB0 buffer

REGISTER 21-15: CxBUFPNT4: ECANx FILTER 12-15 BUFFER POINTER REGISTER 4

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F15BP<3:0>				F14BP<3:0>			
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F13BP<3:0>				F12BP<3:0>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-12 **F15BP<3:0>:** RX Buffer Mask for Filter 15 bits
1111 = Filter hits received in RX FIFO buffer
1110 = Filter hits received in RX Buffer 14
•
•
•
0001 = Filter hits received in RX Buffer 1
0000 = Filter hits received in RX Buffer 0

bit 11-8 **F14BP<3:0>:** RX Buffer Mask for Filter 14 bits (same values as bits<15:12>)

bit 7-4 **F13BP<3:0>:** RX Buffer Mask for Filter 13 bits (same values as bits<15:12>)

bit 3-0 **F12BP<3:0>:** RX Buffer Mask for Filter 12 bits (same values as bits<15:12>)

REGISTER 26-2: CRCCON2: CRC CONTROL REGISTER 2

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	DWIDTH4	DWIDTH3	DWIDTH2	DWIDTH1	DWIDTH0
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	PLEN4	PLEN3	PLEN2	PLEN1	PLEN0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12-8 **DWIDTH<4:0>:** Data Width Select bits
These bits set the width of the data word (DWIDTH<4:0> + 1).

bit 7-5 **Unimplemented:** Read as ‘0’

bit 4-0 **PLEN<4:0>:** Polynomial Length Select bits
These bits set the length of the polynomial (Polynomial Length = PLEN<4:0> + 1).

NOTES:

TABLE 27-1: CONFIGURATION BYTE REGISTER MAP

File Name	Address	Device Memory Size (Kbytes)	Bits 23-8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Reserved	0057EC	32	—	—	—	—	—	—	—	—	—
	00AFEC	64									
	0157EC	128									
	02AFEC	256									
	0557EC	512									
Reserved	0057EE	32	—	—	—	—	—	—	—	—	—
	00AFEE	64									
	0157EE	128									
	02AFEE	256									
	0557EE	512									
FICD	0057F0	32	—	Reserved(3)	—	JTAGEN	Reserved(2)	Reserved(3)	—	ICS<1:0>	
	00AFF0	64									
	0157F0	128									
	02AFF0	256									
	0557F0	512									
FPOR	0057F2	32	—	WDTWIN<1:0>		ALTI2C2	ALTI2C1	Reserved(3)	—	—	—
	00AFF2	64									
	0157F2	128									
	02AFF2	256									
	0557F2	512									
FWDT	0057F4	32	—	FWDTEN	WINDIS	PLLKEN	WDTPRE	WDTPOST<3:0>			
	00AFF4	64									
	0157F4	128									
	02AFF4	256									
	0557F4	512									
FOSC	0057F6	32	—	FCKSM<1:0>		IOL1WAY	—	—	OSCIOFNC	POSCMD<1:0>	
	00AFF6	64									
	0157F6	128									
	02AFF6	256									
	0557F6	512									
FOSCSEL	0057F8	32	—	IESO	PWMLOCK(1)	—	—	—	FNOSC<2:0>		
	00AFF8	64									
	0157F8	128									
	02AFF8	256									
	0557F8	512									
FGS	0057FA	32	—	—	—	—	—	—	—	GCP	GWRP
	00AFFA	64									
	0157FA	128									
	02AFFA	256									
	0557FA	512									
Reserved	0057FC	32	—	—	—	—	—	—	—	—	—
	00AFFC	64									
	0157FC	128									
	02AFFC	256									
	0557FC	512									
Reserved	057FFE	32	—	—	—	—	—	—	—	—	—
	00AFFE	64									
	0157FE	128									
	02AFFE	256									
	0557FE	512									

Legend: — = unimplemented, read as '1'.

Note 1: This bit is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

2: This bit is reserved and must be programmed as '0'.

3: These bits are reserved and must be programmed as '1'.

30.1 DC Characteristics

TABLE 30-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range (in Volts)	Temp Range (in °C)	Maximum MIPS
			dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X
—	3.0V to 3.6V(1)	-40°C to +85°C	70
—	3.0V to 3.6V(1)	-40°C to +125°C	60

Note 1: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Device functionality is tested but not characterized. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

TABLE 30-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min.	Typ.	Max.	Unit
Industrial Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+125	°C
Operating Ambient Temperature Range	TA	-40	—	+85	°C
Extended Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+140	°C
Operating Ambient Temperature Range	TA	-40	—	+125	°C
Power Dissipation: Internal chip power dissipation: PINT = VDD x (IDD – Σ IOH) I/O Pin Power Dissipation: I/O = Σ ({VDD – VOH} x IOH) + Σ (VOL x IOL)	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ – TA)/θJA			W

TABLE 30-3: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Typ.	Max.	Unit	Notes
Package Thermal Resistance, 64-Pin QFN	θJA	28.0	—	°C/W	1
Package Thermal Resistance, 64-Pin TQFP 10x10 mm	θJA	48.3	—	°C/W	1
Package Thermal Resistance, 48-Pin UQFN 6x6 mm	θJA	41	—	°C/W	1
Package Thermal Resistance, 44-Pin QFN	θJA	29.0	—	°C/W	1
Package Thermal Resistance, 44-Pin TQFP 10x10 mm	θJA	49.8	—	°C/W	1
Package Thermal Resistance, 44-Pin VTLA 6x6 mm	θJA	25.2	—	°C/W	1
Package Thermal Resistance, 36-Pin VTLA 5x5 mm	θJA	28.5	—	°C/W	1
Package Thermal Resistance, 28-Pin QFN-S	θJA	30.0	—	°C/W	1
Package Thermal Resistance, 28-Pin SSOP	θJA	71.0	—	°C/W	1
Package Thermal Resistance, 28-Pin SOIC	θJA	69.7	—	°C/W	1
Package Thermal Resistance, 28-Pin SPDIP	θJA	60.0	—	°C/W	1

Note 1: Junction to ambient thermal resistance, Theta-JA (θJA) numbers are achieved by package simulations.

TABLE 30-45: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK1 Input Frequency	—	—	Lesser of FP or 15	MHz	**(Note 3)**
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS1}$ ↓ to SCK1 ↑ or SCK1 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS1}$ ↑ to SDO1 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{SS1}$ ↑ after SCK1 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**
SP60	TssL2doV	$\overline{SDO1}$ Data Output Valid after $\overline{SS1}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 66.7 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

TABLE 30-53: OP AMP/COMPARATOR SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)(1) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
Op Amp DC Characteristics							
CM40	VCMR	Common-Mode Input Voltage Range	AVSS	—	AVDD	V	
CM41	CMRR	Common-Mode Rejection Ratio(3)	—	40	—	db	VCM = AVDD/2
CM42	VOFFSET	Op Amp Offset Voltage(3)	—	±5	—	mV	
CM43	VGAIN	Open-Loop Voltage Gain(3)	—	90	—	db	
CM44	IOS	Input Offset Current	—	—	—	—	See pad leakage currents in Table 30-11
CM45	IB	Input Bias Current	—	—	—	—	See pad leakage currents in Table 30-11
CM46	IOUT	Output Current	—	—	420	µA	With minimum value of RFEEDBACK (CM48)
CM48	RFEEDBACK	Feedback Resistance Value	8	—	—	kΩ	
CM49a	VOADC	Output Voltage Measured at OAx Using ADC(3,4)	AVSS + 0.077 AVSS + 0.037 AVSS + 0.018	— — —	AVDD – 0.077 AVDD – 0.037 AVDD – 0.018	V V V	IOUT = 420 µA IOUT = 200 µA IOUT = 100 µA
CM49b	VOUT	Output Voltage Measured at OAxOUT Pin(3,4,5)	AVSS + 0.210 AVSS + 0.100 AVSS + 0.050	— — —	AVDD – 0.210 AVDD – 0.100 AVDD – 0.050	V V V	IOUT = 420 µA IOUT = 200 µA IOUT = 100 µA
CM51	RINT1(6)	Internal Resistance 1 (Configuration A and B)(3,4,5)	198	264	317	Ω	Min = -40ºC Typ = +25ºC Max = +125ºC

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

3: Parameter is characterized but not tested in manufacturing.

4: See Figure 25-6 for configuration information.

5: See Figure 25-7 for configuration information.

6: Resistances can vary by ±10% between op amps.

TABLE 30-54: OP AMP/COMPARATOR VOLTAGE REFERENCE SETTLING TIME SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions (see Note 2): 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
VR310	TSET	Settling Time	—	1	10	μs	**(Note 1)**

Note 1: Settling time is measured while CVRR = 1 and CVR<3:0> bits transition from '0000' to '1111'.

2: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

TABLE 30-55: OP AMP/COMPARATOR VOLTAGE REFERENCE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions (see Note 1): 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
VRD310	CVRES	Resolution	CVRSRC/24	—	CVRSRC/32	LSb	
VRD311	CVRAA	Absolute Accuracy(2)	—	±25	—	mV	CVRSRC = 3.3V
VRD313	CVRSRC	Input Reference Voltage	0	—	AVDD + 0.3	V	
VRD314	CVROUT	Buffer Output Resistance(2)	—	1.5k	—	Ω	

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: Parameter is characterized but not tested in manufacturing.

FIGURE 32-9: TYPICAL FRC FREQUENCY @ V_{DD} = 3.3V

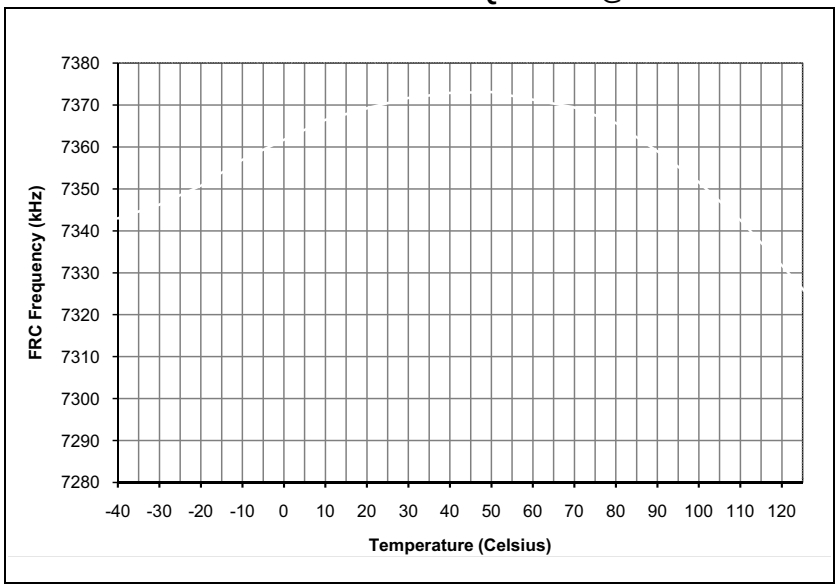


FIGURE 32-10: TYPICAL LPRC FREQUENCY @ V_{DD} = 3.3V

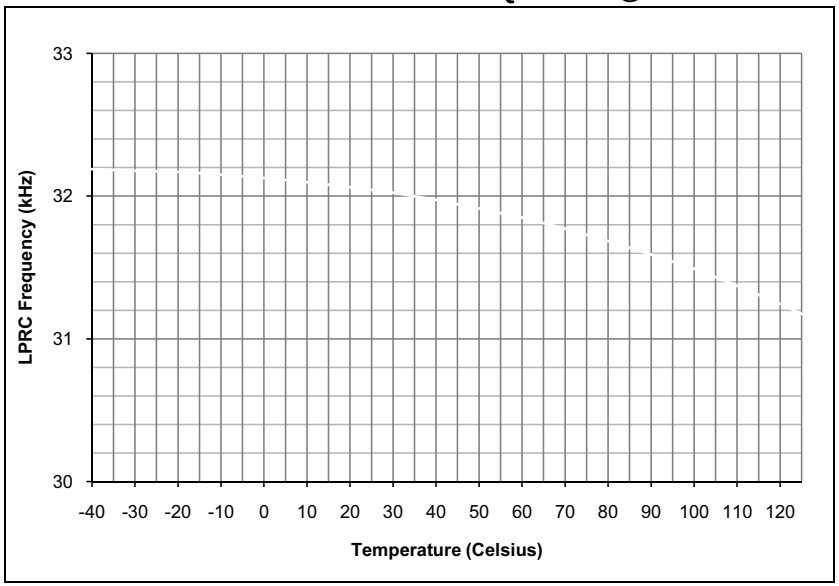
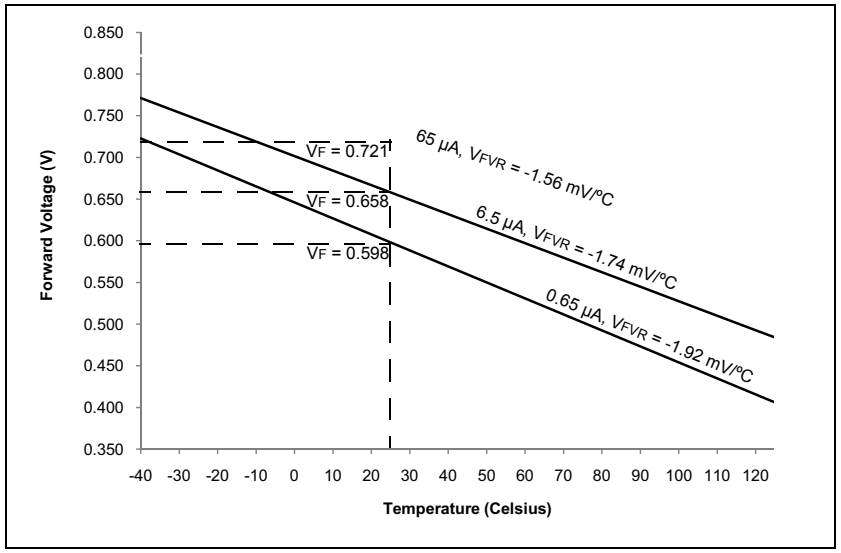


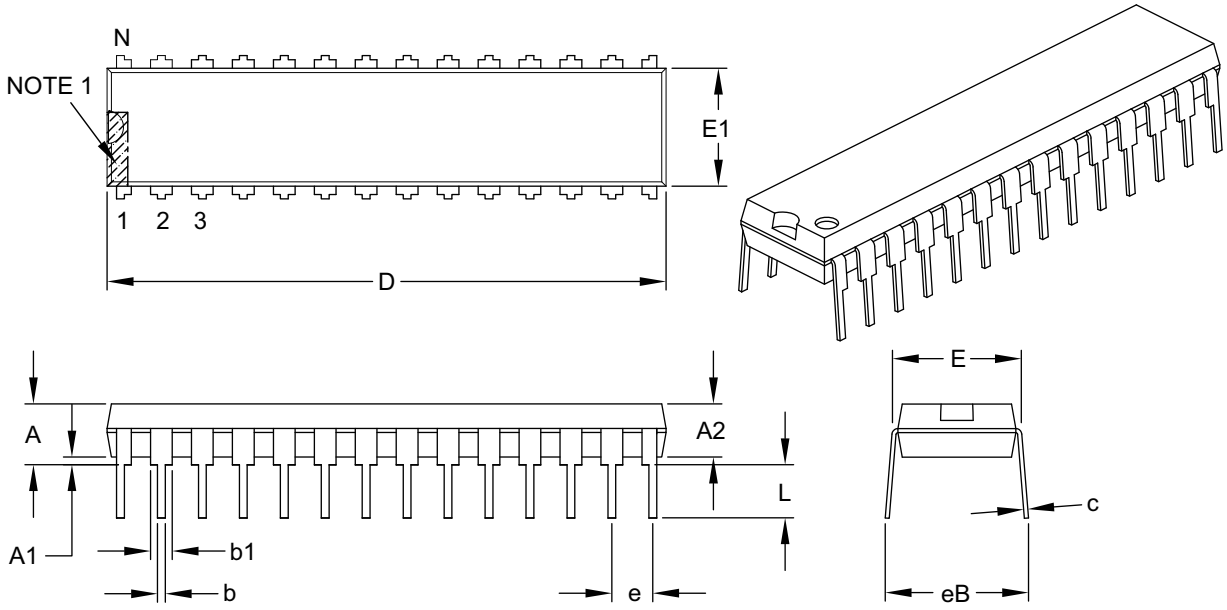
FIGURE 32-11: TYPICAL CTMU TEMPERATURE DIODE FORWARD VOLTAGE



33.2 Package Details

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

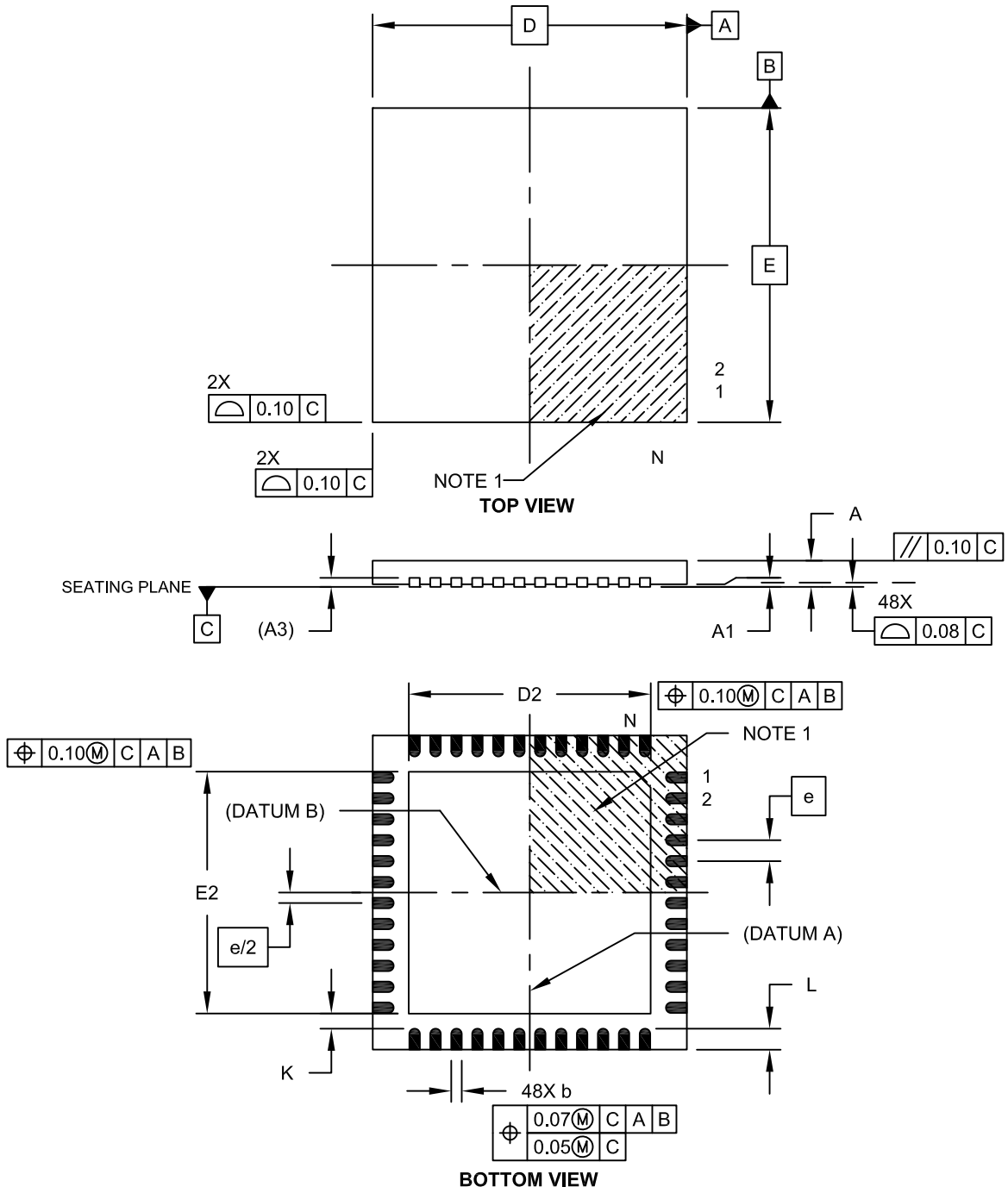
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

48-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) – 6x6x0.5 mm Body [UQFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-153A Sheet 1 of 2